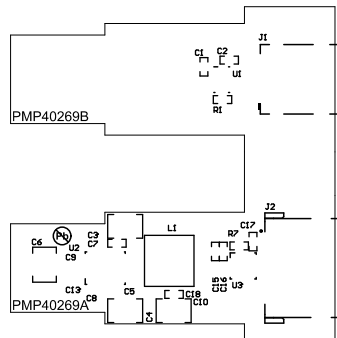
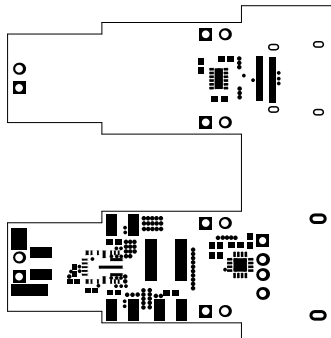


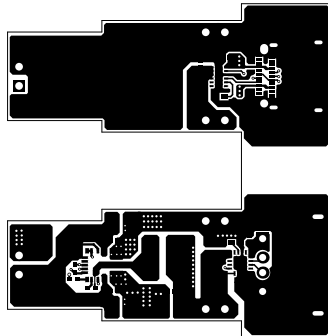
ZZ3
ZZ4



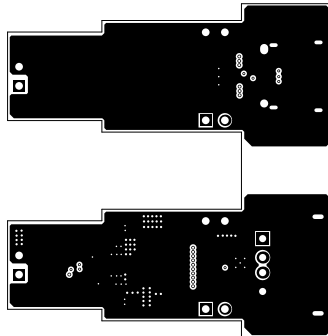
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40269		
PLOT NAME = Top Overlay	GENERATED : 8/17/2017 5:10:12 PM		TEXAS INSTRUMENTS



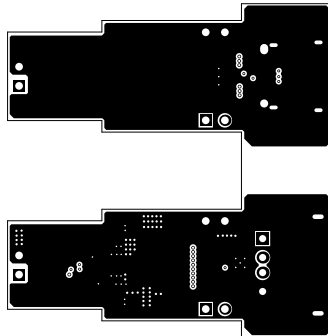
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40269		
PLOT NAME = Top Solder Mask	GENERATED : 8/17/2017 5:10:13 PM		TEXAS INSTRUMENTS



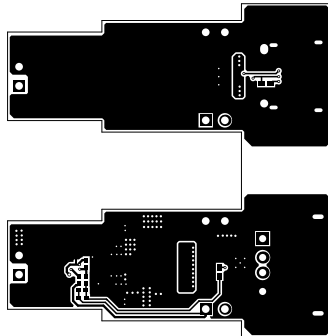
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40269		
PLOT NAME = Top Layer	GENERATED : 8/17/2017 5:10:15 PM		TEXAS INSTRUMENTS



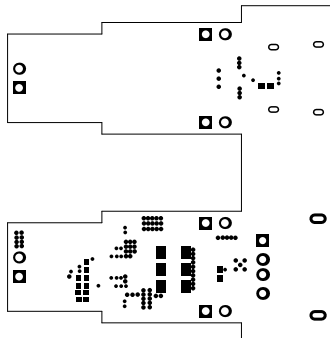
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40269		
PLOT NAME = Signal Layer 1	GENERATED : 8/17/2017 5:10:16 PM		TEXAS INSTRUMENTS



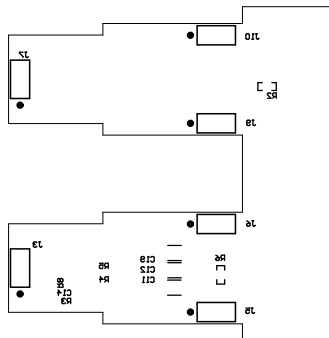
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40269		
PLOT NAME = Signal Layer 2	GENERATED : 8/17/2017 5:10:17 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40269		
PLOT NAME = Bottom Layer	GENERATED : 8/17/2017 5:10:18 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40269		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/17/2017 5:10:19 PM		TEXAS INSTRUMENTS



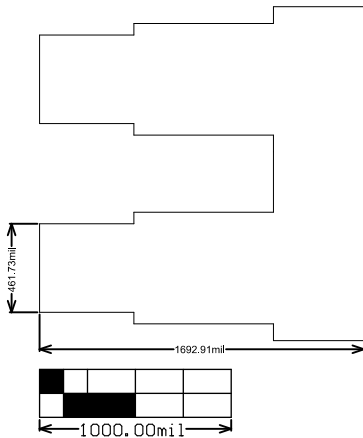
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40269		
PLOT NAME = Bottom Overlay	GENERATED : 8/17/2017 5:10:21 PM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
■	1	25.59mil (0.650mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	34	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	73	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	37.00mil (0.940mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	12	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	1	25.59mil (0.650mm)	NPTH	Slot	Top Layer - Bottom Layer	
○	4	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	
⊗	2	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
131 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40269		
PLOT NAME = Drill Drawing	GENERATED : 8/17/2017	5:10:22 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40269	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40269		
PLOT NAME = Board Dimensions	GENERATED : 8/17/2017	5:10:24 PM	TEXAS INSTRUMENTS

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